

AMENDMENTS TO THE CLAIMS:

The following listing of claims replaces all prior listings, and all prior versions, of claims in the application.

Listing of Claims:

Claims 1.-31. (Cancelled)

32. (Currently Amended) A substrate for mounting semiconductor devices thereon having an insulating supporting member and plural sets of wirings, and further comprising:

a semiconductor device mounting region and a resin-sealing semiconductor package region outside of said semiconductor device mounting region,

wherein said plural sets of wirings comprise a predetermined wiring pattern including wire-bonding terminals and external connection terminals,

wherein said wire bonding terminals are provided in said semiconductor package region and said external connection terminals are provided in-only within said semiconductor device mounting region,

wherein said substrate includes a plurality of said semiconductor device mounting regions, and

wherein said plurality of said semiconductor device mounting regions respectively have blocks of said wirings, each having a same pattern.

33. (Previously Presented) A substrate for mounting semiconductor devices thereon, having an insulating supporting member and plural sets of wirings, wherein:

said wirings form a predetermined wiring pattern including a wire bonding terminal and an external connection terminal; and

said external connection terminal is provided only inside of said wire bonding terminal.

34. (Previously Presented) The substrate for mounting semiconductor device thereon according to claim 33, comprising a plurality of said wiring patterns comprised of a plurality of said wirings arranged in rows and columns.

35. (Previously Presented) The substrate for mounting semiconductor devices thereon according to claim 33, wherein said wire-bonding terminal comprises a nickel layer and a gold plate layer on its surface.

36. (Previously Presented) The substrate for mounting semiconductor devices thereon according to claim 33,

wherein said external connection terminal is one of a plurality of external connection terminals, exposed on a surface of said insulating supporting member, on an opposite side to which said semiconductor device is mounted, and said external connection terminals are arranged in a grid patterns at positions corresponding to a semiconductor device mounting region and a semiconductor package region of said substrate.

37. (Previously Presented) A semiconductor package produced by a method comprising the steps of:

mounting a semiconductor device on each of said plural semiconductor device mounting regions of the substrate for mounting the semiconductor device thereon according to claim 33 by employing a die-bonding material,

electrically connecting the semiconductor device with the wire-bonding terminals by wire-bonding,

sealing said semiconductor package region including said semiconductor device with a sealing resin connected in one-piece;

forming solder bumps on said external connection terminals; and

cutting said substrate for mounting the semiconductor device thereon and said sealing resin in one operation to be separated into the individual semiconductor package.